Table 1: Evolution of High-Density Micron SLC/MLC Devices

	2006	*2007*	*2008*	*2009*	*2010*
Characteristics					
Monolithic Die Density	2Gb	**8Gb**	8Gb/**16Gb**	16Gb/**32Gb**	32Gb/**64Gb**
Geometry (nm)	90	72	50	34	25
^{t}PROG (µs TYP)	~300	~**700**	~300/~**900**	~300/~**900**	~300/~**1300**
Page Size (bytes)	2112	2112	4314	4320	8640
Number of Planes	1	2	2	2	2
Number of Pages (SLC/MLC)	64	**128**	64/**128**	128/**256**	128/**256**
Block Size (KB)	128	**256**	256/**512**	512/**1024**	1024/**2048**
^{t}R (µs)	25	**50**	25/**50**	25/**50**	35/**75**
ECC Required/ Code Word	1/528	**4/528**	4/539, **8/539**	4/540, **12/540**	8/540, **24/1080**
NOP (Number of Partial-Page Operations)	8	**1**	4/**1**	4/**1**	4/**1**
Endurance	100,000	**10,000**	100,000/ **10,000**	100,000/ **5000**	60,000/ **3000**
Interface (MT/s)	SDR 40	SDR 50	SDR 50	DDR 166	DDR 200
Packages	TSOP	TSOP	TSOP	TSOP, LGA, BGA*	TSOP, LGA, BGA*
Temperature Range	C	C	C	C, I	C, I

*Notes: Timeline years are approximate. Values specific to MLC devices are in **bold**. Shaded columns identify the NAND devices used for most of our comparisons. *Up to 8-die BGA packages offered.*